



SOT457

plastic surface-mounted package (TSOP6); 6 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	TSOP6
Package type industry code	TSOP6
Package style descriptive code	SOT (small outline transistor)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEITA package outline code	SC-74
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		2.7	-	2.9	3.1	mm
E	package width		1.3	-	1.5	1.7	mm
A	seated height		0.9	-	1	1.1	mm
e	nominal pitch		-	-	[tbd]	-	mm
n ₂	actual quantity of termination		-	-	6	-	



2. Package outline

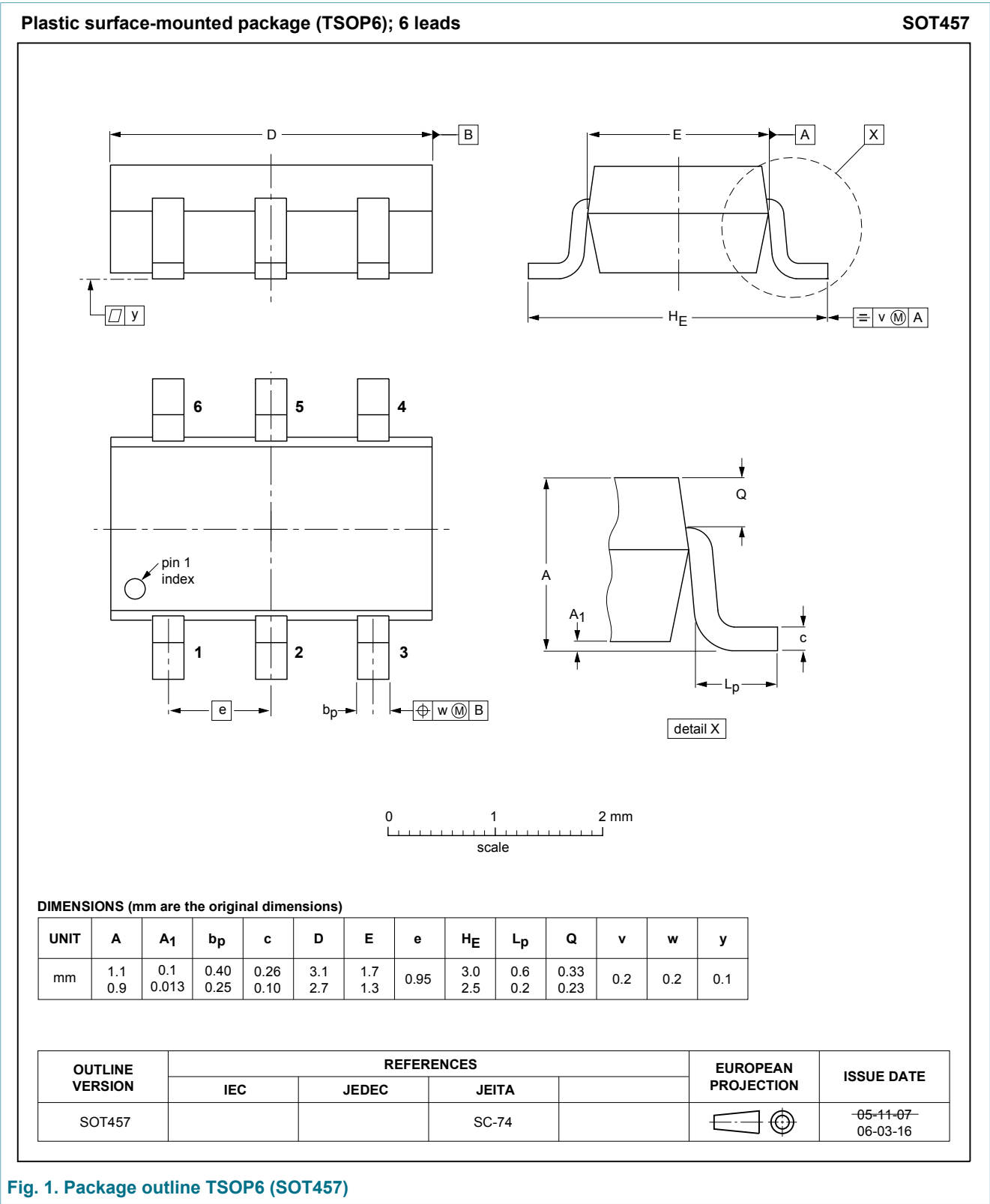


Fig. 1. Package outline TSOP6 (SOT457)

3. Soldering

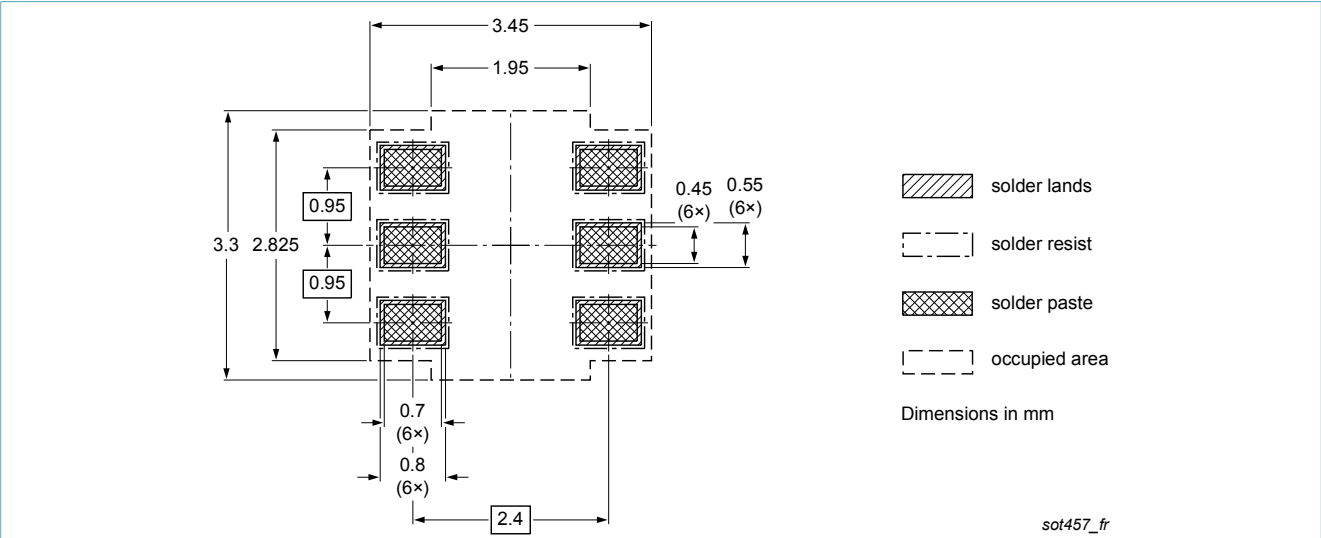


Fig. 2. Reflow soldering footprint for TSOP6 (SOT457)

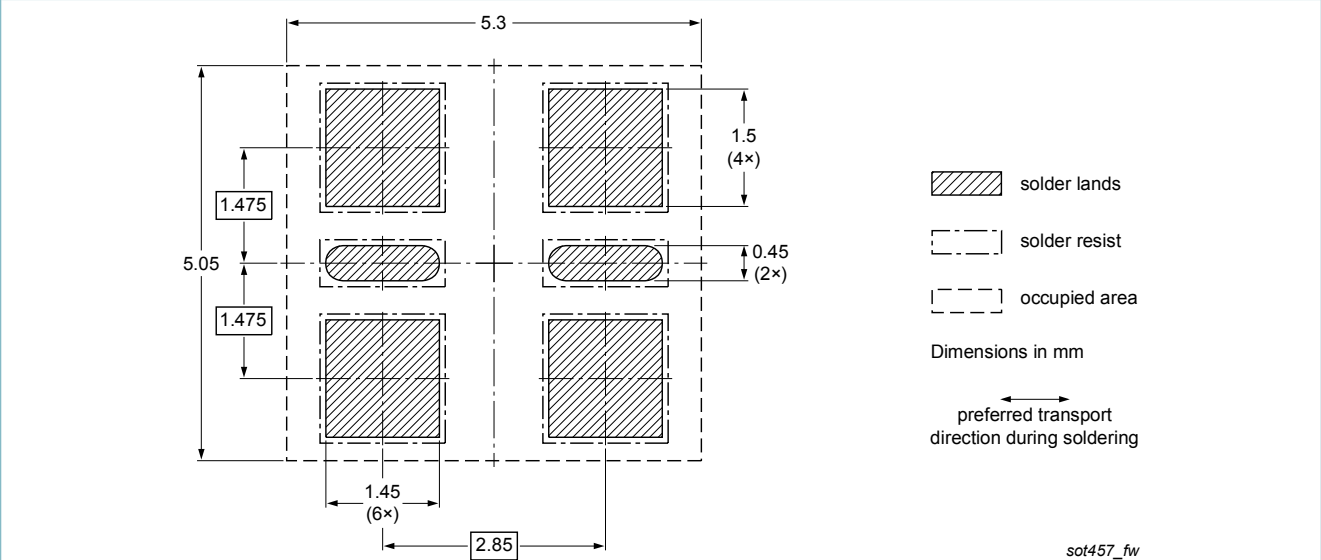


Fig. 3. Wave soldering footprint for TSOP6 (SOT457)

4. Legal information

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